



JF 3723

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

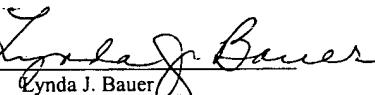
Applicant: RAEDER Examiner: Nguyen, D.

Serial No.: 09/383,876 Group Art Unit: 3723

Filed: August 26, 1999 Docket No.: AMDA.316PA

Title: POLISHING UNIFORMITY VIA PAD CONDITIONING

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on January 19, 2001.

By: 
Cynda J. Bauer

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OFFICE ACTION RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated October 19, 2000, please amend the above-identified patent application as follows:

In The Figures

Please replace Fig. 2 with the attached replacement sheet to show the changes reflected thereon in red ink.

In The Specification

Please amend the specification as follows:

Page 8, line 3, after "present invention.", insert ~~+ FIG. 2 shown the wafer carrier 130~~

b1 (along with wafer 135) misaligned over and with respect to the center of the pad 140a. --

Page 9, line 17, please delete "A" and "B".

Page 9, lines 16-19, after each occurrence of "pad", insert -- 140a --, and after each occurrence of "edge", please insert -- 230 --.